<table>
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<tr>
<th>ALL PARTS USED FROM TOP SIDE</th>
<th>REMED TO TIIN-HG153</th>
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<td>LIVER HARE = Top Solder</td>
<td>TIIN-0015</td>
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<td>SLOT NAME = Top Solder Napl</td>
<td>GEVEN15542 4-4-2018</td>
<td>103.7445 NM</td>
<td>TEXAS INSTRUMENTS</td>
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